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Intel Acquires Industry-Leading, High-Performance Computing Interconnect Technology and Expertise

Key Assets from Cray Accelerate Intel's Drive to Achieve ExaFLOPS Performance

SANTA CLARA, Calif.--(BUSINESS WIRE)-- Intel Corporation today announced it has entered into a definitive agreement with Cray Inc. to acquire certain assets related to its high-performance computing (HPC) interconnect program. With the agreement, Intel gains access to Cray's world-class interconnect personnel and intellectual property.

The Cray interconnect team is responsible for the award-winning¹ Gemini interconnect as well as the upcoming Aries interconnect, designed to work in Cray's next-generation supercomputer, codenamed "Cascade," which will integrate Intel® Xeon® processors. The transaction is expected to close before the end of the current quarter, subject to customary closing conditions being met.

"Delivering continued advancement in high-performance computing, including breaking the Exascale barrier, requires tremendous innovation in interconnect technology," said Diane Bryant, vice president and general manager of Intel's Datacenter and Connected System Group. "The acquisition of Cray's industry-leading interconnect technology and expertise provides exceptional strategic assets that further enhance Intel's HPC portfolio. We're excited about the value this will allow us to bring to our customers."

About Intel

Intel (NASDAQ:INTC) is a world leader in computing innovation. The company designs and builds the essential technologies that serve as the foundation for the world's computing devices. Additional information about Intel is available at newsroom.intel.com and blogs.intel.com.

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¹ *<http://investors.cray.com/phoenix.zhtml?c=98390&p=irol-newsArticle&ID=1496834&highlight=>

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